PMP7294_REVB BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
2	C1, C200	0.047uF	Capacitor, Ceramic, 100V, X7R, 15%	1206	STD	STD
1	C10	330pF	Capacitor, Ceramic, 3kV, NP0, C0G, 10%	1808	Std	Std
1	C11	47uF	Capacitor, Aluminum, 16V, 20%	0.201 x 0.262 inch	EEVFK1C470UR	Panasonic
1	C14	1uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	STD	STD
1	C15		Capacitor, Ceramic, 50V, C0G, 10%	0603	STD	STD
1	C16	0.047uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
8	C2, C3, C8, C9, C18, C19, C20, C21		Capacitor, Ceramic, 50V, X7R, 15%	1210	STD	STD
1	C201	1000pF	Capacitor, Ceramic, 200V, C0G, 5%	0805	STD	STD
1	C202	47pF	Capacitor, Ceramic, 50V, C0G, 5%	0603	STD	STD
1	C25		CAP ALUM 470UF 35V 20% SMD	0.543 x 0.543	EEV-FK1V471Q	Panasonic
1	C26		CAP ALUM 100UF 35V 20% SMD	0.328 x 0.390 inch	EEV-FK1V101XP	Panasonic
2	C5, C6		Capacitor, Ceramic, 50V, X7R, 15%	0603	STD	STD
4	C7, C12, C13, C17		Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
2	D200, D201		DIODE SCHOTTKY DUAL 200V D2PAK	TO-263AB	MBRB20200CT	On Semiconductor
2	D202, D203		DIODE ULTRA FAST 1A 200V SMA	SMA	ES1D-13	Diodes Inc.
1	D204		Diode, Zener, 12-V	SOT23	STD	STD
4	D4, D5, D8, D9		Diode, Switching, 100-V, 200-mA, 225-mW,	SOD-123	MMSD914T1	On Semi
2	J2, J3	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
1	L2		Inductor, Power Coke	21.5x21.8 mm	7443634700	Wurth
1	L3		Inductor, 9A	11.4 x 12.1 mm	7443321000	Wurth
2	Q1, Q9		MOSFET N-CH 80V 8-SOIC	SO8	AO4444	Alpha & Omega Semiconductor Inc
1	Q10		TRANSISTOR, NPN, HIGH-PERFORMANCE, 500mA	SOT-23	MMBT2222A	Fairchild
1	Q11		Transistor, PNP, -60V, -600mA, 225-W	SOT23	MMBT2907ALT1	On Semi
1	Q2	FDC3535	MOSFET P-CH 80V 6-SSOT	SuperSOT-6	FDC3535	Fairchild
1	Q200	FZT651TA	TRANS NPN HP 60V 3000MA SOT-223	SOT223	FZT651TA	Diodes Inc.
	R1	1k	Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R10		Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R100		Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R14		Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R15		Resistor, Chip, 1/16W, 1%	0603	STD	STD
2	R16, R24		Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R17		Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R18	2.05k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R20		Resistor, Metal Film, 1/4 watt, 5%	1206	Std	Std
1	R200		Resistor, Chip, 1W, 5%	2512	STD	STD
1	R201		Resistor, Metal Film, 1/4 watt, 5%	1206	Std	Std
1	R21		Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R3		Resistor, 1/4W, 5%	1210	Std	Std
3	R4, R5, R11	10k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
3	R6, R8, R23		Resistor, Chip, 1/16W, 1%	0603	STD	STD
-	R7, R12, R19		Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R9		Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	T2		Transformer, Current Sense		749251100	Wurth
1	Т3	40 uH	Transformer,	27X33 mm	750312917	WE
3	TP1, TP2, TP4		Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	TP3, TP5	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1		IC, Current-Mode Active Clamp PWM Controller	PW20	UCC2897APW	TI
1	U3		IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	TI
1	U4	TCMT1107	IC, Photocoupler	MF4	TCMT1107	Vishay

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